

### **REMARKS**

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-7, 9-15, 21 and 22 are pending in the present application. Claims 1, 8, 11-14 and 21 have been amended and claim 9 has been canceled by the present amendment.

In the outstanding Office Action, claims 1, 8, 21 and 22 were rejected under 35 U.S.C. § 103(a) as unpatentable over Ueda et al. in view of Hibino et al.; and claims 1-15, 21 and 22 were rejected under 35 U.S.C. § 103(a) as unpatentable over Applicants admitted prior art (APA) in view of Ueda et al. and Hibino et al.

Applicant thanks the Examiner for discussing this application with Applicant's representative on July 29, 2008. During the discussion, the differences between the present invention and the applied art were discussed. No agreement was reached pending the Examiner's further review when a response is filed.

As discussed with the Examiner, claim 1 has been amended to clarify that the first, second and third metal layers comprise a same step shape that are symmetrical with respect to each other, the second metal layer extends beyond edges of the first semiconductor layer, the first metal layer extends only to edges of the first semiconductor layer, and the first and third metal layers do not contact each other. Claim 1 also recites that the display device includes a data pad over the substrate including the second and third metal layers. Independent claims 8 and 21 also include the features regarding the first, second and third metal layers being formed to have a same step shape as described above.

These features are supported by at least Figure 6 and the corresponding description in the specification. For example, Figure 6 illustrates the first, second and third metal layers (59a1, 59a2; 59b1, 59b2; and 59c1, 59c2) comprise a same step shape that are symmetrical with respect to each other, the second metal layer (59b1, 59b2) extends beyond edges of the first semiconductor layer (45), the first metal layer (59a1, 59a2) extends only to edges of the first semiconductor layer (45), and the first and third metal layers (59a1, 59a2 and 59c1, 59c2) do not contact each other.

On the contrary, as shown in Figure 15 of Ueda et al., the first and second metal layers do not have a step shape and are connected to each other. The first and second metal layers in Ueda also do not extend only to the first semiconductor layer and beyond the edges of the first semiconductor layer as claimed. Hibino et al. and APA also do not teach or suggest this feature.

Accordingly, it is respectfully submitted independent claims 1, 8 and 21 and each of the claims depending therefrom are allowable.

**CONCLUSION**

All of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicants therefore respectfully request that the Examiner reconsider all presently outstanding rejections and that they be withdrawn. It is believed that a full and complete response has been made to the Office Action, and as such, the present application is in condition for allowance.

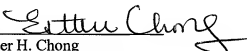
If the Examiner believes, for any reason, that personal communication will expedite prosecution of this application, the Examiner is invited to telephone Robert J. Webster, Registration No. 46,472, at (703) 205-8000, in the Washington, D.C. area.

Prompt and favorable consideration of this Amendment is respectfully requested.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17; particularly, extension of time fees.

Dated: September 11, 2008

Respectfully submitted,

By   
Esther H. Chong  
Registration No.: 40,953  
BIRCH, STEWART, KOLASCH & BIRCH, LLP  
8110 Gatehouse Rd  
Suite 100 East  
P.O. Box 747  
Falls Church, Virginia 22040-0747  
(703) 205-8000  
Attorney for Applicants